SLLS044D - NOVEMBER 1988 - REVISED DECEMBER 1999

 μv_{cc}

GND

7 **|**] B

6 🛮 A

D OR P PACKAGE (TOP VIEW)

RE

DE [] 3

D

- Bidirectional Transceiver
- Meets or Exceeds the Requirements of TIA/EIA-422-B, TIA/EIA-485-A, and ITU Recommendation V.11
- High-Speed Advanced Low-Power Schottky Circuitry
- Low Skew . . . 6 ns Max
- Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments
- Low Supply-Current Requirements . . .
 30 mA Max
- Wide Positive and Negative Input/Output Bus-Voltage Ranges
- Driver Output Capacity . . . ±60 mA
- Thermal-Shutdown Protection
- Driver Positive and Negative Current Limiting
- Receiver Input Impedances . . . 12 kΩ Min
- Receiver Input Sensitivity . . . ±200 mV Max
- Receiver Input Hysteresis . . . 120 mV Typ
- Fail Safe . . . High Receiver Output With Inputs Open
- Operates From a Single 5-V Supply
- Glitch-Free Power-Up and Power-Down Protection
- Interchangeable With National DS3695 and DS3695A

description

The TL3695 differential bus transceiver is designed for bidirectional data communication on multipoint bus-transmission lines. It is designed for balanced transmission lines and meets TIA/EIA-422-B, TIA/EIA-485-A, and ITU Recommendation V.11.

The TL3695 combines a 3-state differential line driver and a differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, which can be externally connected together to function as a directional control. The driver differential outputs and the receiver differential inputs are connected internally to form a differential input/output (I/O) bus port that is designed to offer minimum loading to the bus when the driver is disabled or $V_{\rm CC} = 0$. This port features wide positive and negative common-mode voltage ranges, making the device suitable for party line applications.

The TL3695 is characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



AVAILABLE OPTIONS

	PACKAGED DEVICES						
TA	SMALL OUTLINE	PLASTIC DIP					
	(D)	(P)					
0°C to 70°C	TL3695D	TL3695P					

The D package is available taped and reeled. Add the suffix R to device type (e.g., TL3695DR).

Function Tables

DRIVER

INPUT	ENABLE	OUTPUTS			
D	DE	Α	В		
Н	Н	Н	L		
L	Н	L	Н		
X	L	Z	Z		

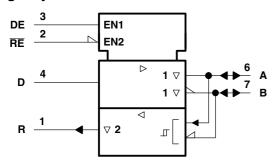
H = high level, L = low level, ? = indeterminate, X = irrelevant, Z = high impedance (off)

RECEIVER

DIFFERENTIAL INPUTS A – B	ENABLE RE	OUTPUT R
$V_{ID} \ge 0.2 \text{ V}$	L	Н
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$	L	?
$V_{ID} \le -0.2 \text{ V}$	L	L
X	Н	Z
Inputs open	L	Н

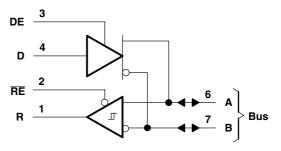
H = high level, L = low level, ? = indeterminate, X = irrelevant, Z = high impedance (off)

logic symbol†

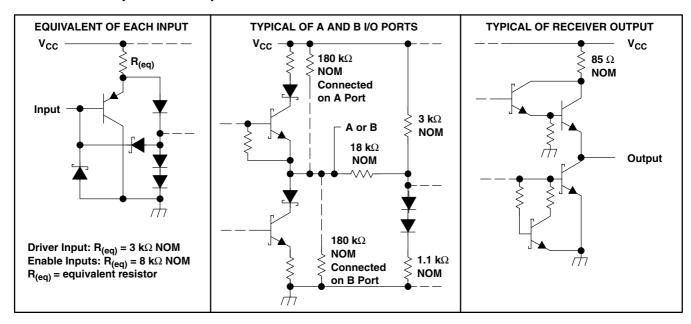


 † This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematic of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	7 V
Voltage range at any bus terminal	–10 V to 15 V
Enable input voltage, V _I	5.5 V
Operating free-air temperature range, T _A	0°C to 70°C
Package thermal impedance, θ _{JA} (see Note 2): D package	97°C/W
PW package	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.

^{2.} The package thermal impedance is calculated in accordance with JESD 51.

TL3695 DIFFERENTIAL BUS TRANSCEIVER

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recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.75	5	5.25	٧
Nelhana at any hya tamainal (anayatah ay asaman mada) Man M				12	V
Voltage at any bus terminal (separately or common mode), V_{I} or V_{IC}				-7	٧
High-level Input voltage, $V_{\rm IH}$	D, DE, and RE	2			٧
Low-level Input voltage, V _{IL}	D, DE, and RE			8.0	V
Differential input voltage, V _{ID} (see Note 3)				±12	V
High level colors a common I	Driver			- 60	mA
High-level output current, I _{OH}	Receiver			- 400	μΑ
Low book orders and the	Driver			60	A
Low-level output current, I _{OL}	Receiver			8	mA
Operating free-air temperature, T _A				70	°C

NOTE 3: Differential input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CON	DITIONS†	MIN	TYP‡	MAX	UNIT
V _{IK}	Input clamp voltage	I _I = – 18 mA				-1.5	V
Vo	Output voltage	I _O = 0		0		6	V
V _{OD1}	Differential output voltage	I _O = 0		1.5		5	V
V _{OD2}	Differential output voltage	$R_L = 100 \Omega$,	See Figure 1	1/2 V _{OD1} or 2 [§]			٧
		$R_L = 54 \Omega$,	See Figure 1	1.5	2.5	5	V
V_{OD3}	Differential output voltage	$V_{test} = -7 \text{ V to } 12 \text{ V},$	See Figure 2	1.5		5	V
Δ V _{OD}	Change in magnitude of differential output voltage¶					±0.2	V
V _{OC}	Common-mode output voltage	$R_L = 54 \Omega$,	See Figure 1			3	V
Δ V _{OC}	Change in magnitude of common-mode output voltage¶					±0.2	V
Io	Output current	Output disabled, See Note 4	$V_O = 12 \text{ V}$ $V_O = -7 \text{ V}$			1 -0.8	mA
I _{IH}	High-level input current	V _I = 2.4 V				20	μΑ
I _{IL}	Low-level input current	V _I = 0.4 V				-200	μΑ
		V _O = -6 V				-250	
١.	0	V _O = 0				-150	
los	Short-circuit output current#	$V_O = V_{CC}$				250	mA
		V _O = 8 V			250		
	Committee accomment	Natari	Outputs enabled		23	50	^
Icc	Supply current	No load	Outputs disabled	-	19	35	mA

[†] The power-off measurement in TIA/EIA-422-B applies to disabled outputs only and is not applied to combined inputs and outputs.

NOTE 4: This applies for power on and power off. Refer to TIA/EIA-485-A for exact conditions. The TIA/EIA-422-B limit does not apply for a combined driver and receiver terminal.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature

	PARAMETER	TES	T CONDITIONS		MIN	TYP‡	MAX	UNIT
t _{d(OD)}	Differential-output delay time					8	22	ns
	Skew ($ t_{d(ODH)} - t_{d(ODL)} $)	$C_{L1} = C_{L2} = 100 \text{ pF},$	$R_L = 60 \Omega$,	See Figure 3		1	8	ns
t _{t(OD)}	Differential output transition time					8	18	ns
t _{PZH}	Output enable time to high level	C _L = 100 pF,	$R_L = 500 \Omega$,	See Figure 4			50	ns
t _{PZL}	Output enable time to low level	C _L = 100 pF,	$R_L = 500 \Omega$,	See Figure 5			50	ns
t _{PHZ}	Output disable time from high level	C _L = 15 pF,	$R_L = 500 \Omega$,	See Figure 4		8	30	ns
t_{PLZ}	Output disable time from low level	C _L = 15 pF,	$R_L = 500 \Omega$,	See Figure 5		8	30	ns

[‡] All typical values are at V_{CC} = 5 V and T_A = 25°C.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

 $[\]S$ The minimum V_{OD2} with a 100- Ω load is either 1/2 V_{OD1} or 2 V, whichever is greater.

 $[\]P \Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low level

[#] Duration of the short circuit should not exceed one second for this test.

SYMBOL EQUIVALENTS

DATA-SHEET PARAMETER	TIA/EIA-422-B	TIA/EIA-485-A
V _O	V _{oa} , V _{ob}	V_{oa}, V_{ob}
V _{OD1}	V _o	V _o
V _{OD2}	$V_t (R_L = 100 \Omega)$	$V_t (R_L = 54 \Omega)$
V _{OD3}		V _t (test termination measurement 2)
V _{test}		V _{tst}
Δ V _{OD}	$ V_t - \overline{V}_t $	$ V_t - \overline{V}_t $
V _{OC}	V _{os}	V _{os}
Δ V _{OC}	$ V_{os} - \overline{V}_{os} $	$ V_{os} - \overline{V}_{os} $
Ios	I _{sa} ,	
I _O	I _{xa} , I _{xb}	I _{ia} , I _{ib}

RECEIVER SECTION

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST C	ONDITIONS	MIN	TYP†	MAX	UNIT	
V _{IT+}	Positive-going input threshold voltage	$V_0 = 2.7 V$,	$I_0 = -0.4 \text{ mA}$			0.2	V	
V_{IT-}	Negative-going input threshold voltage	$V_O = 0.5 V$,	$I_O = 8 \text{ mA}$	-0.2 [‡]			V	
V_{hys}	Hysteresis voltage (V _{IT+} -V _{IT-})	V _{OC} = 0			70		mV	
V _{IK}	Enable-input clamp voltage	$I_{I} = -18 \text{ mA}$				-1.5	V	
V _{OH}	High-level output voltage	V_{ID} = 200 mV or in I_{OH} = -400 μ A,	V_{ID} = 200 mV or inputs open, I_{OH} = -400 μ A, See Figure 6				٧	
.,		$V_{ID} = -200 \text{ mV},$	I _{OL} = 16 mA			0.5	.,	
V_{OL}	Low-level output voltage	See Figure 6	$I_{OL} = 8 \text{ mA}$			0.45	V	
loz	High-impedance-state output current	$V_O = 0.4 \text{ V to } 2.4 \text{ V}$				±20	μΑ	
		Other input = 0,	V _I = 12 V			1		
Ц	Line input current	See Note 5	$V_I = -7 \text{ V}$			-0.8	mA	
I _{IH}	High-level enable-input current	V _{IH} = 2.7 V	•			20	μΑ	
I _{IL}	Low-level enable-input current	V _{IL} = 0.4 V				-100	μΑ	
rį	Input resistance			12			kΩ	
los	Short-circuit output current§	V _O = 0		-15		-85	mA	
		Noteed	Outputs enabled		23	50	A	
Icc	Supply current	No load	Outputs disabled		19	35	mA	

 $^{^{\}dagger}$ All typical values are at $V_{CC}=5$ V and $T_{A}=25^{\circ}C.$

NOTE 5: This applies for power on and power off. Refer to TIA/EIA-485-A for exact conditions.



[‡] The algebraic convention, in which the less positive (more negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

[§] Duration of the short circuit should not exceed one second for this test.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature range, C_L = 15 pF

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
t _{PLH}	Propagation delay time, low- to high-level output	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V},$		14	37	ns
t _{PHL}	Propagation delay time, high- to low-level output	See Figure 7		14	37	ns
t _{PZH}	Output enable time to high level	Con Figure 0		7	20	ns
t_{PZL}	Output enable time to low level	See Figure 8		7	20	ns
t _{PHZ}	Output disable time from high level	Coo Figure 0		7	16	ns
t_{PLZ}	Output disable time from low level	See Figure 8		8	16	ns

[†] All typical values are at V_{CC} = 5 V and T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION

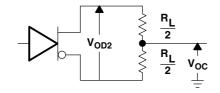


Figure 1. Driver V_{OD} and V_{OC}

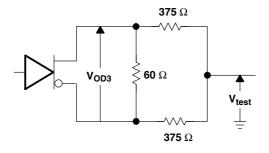
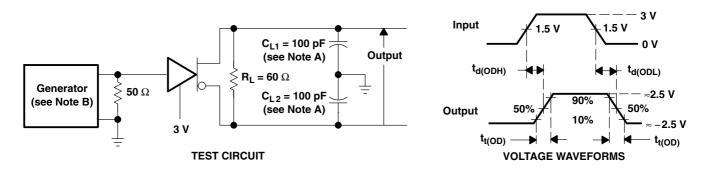


Figure 2. Driver V_{OD3}



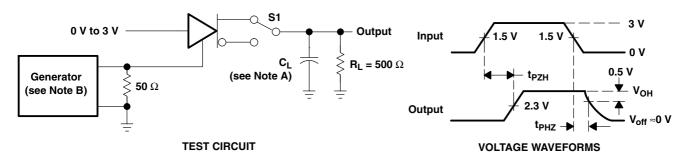
NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_r \leq$ 6 ns, $t_f \leq$ 6 ns, $Z_O = 50 \Omega$.

Figure 3. Driver Differential-Output Test Circuit and Voltage Waveforms



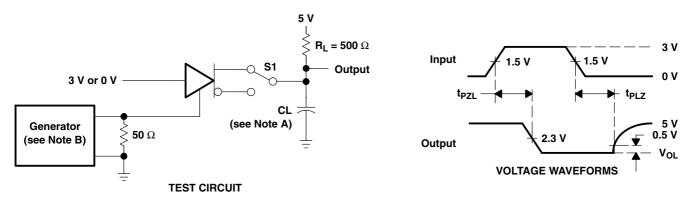
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_r \leq$ 10 ns, $t_f \leq$ 10 ns, $Z_O = 50 \ \Omega$.

Figure 4. Driver Test Circuit and Voltage Waveforms



NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_r \leq$ 10 ns, $t_f \leq$ 10 ns, $Z_O =$ 50 Ω .

Figure 5. Driver Test Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION

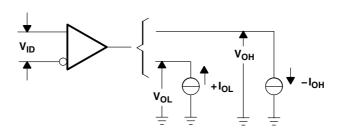
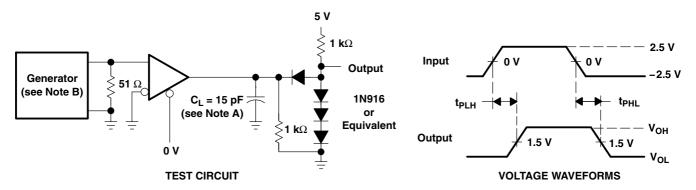


Figure 6. Receiver VOH and VOL

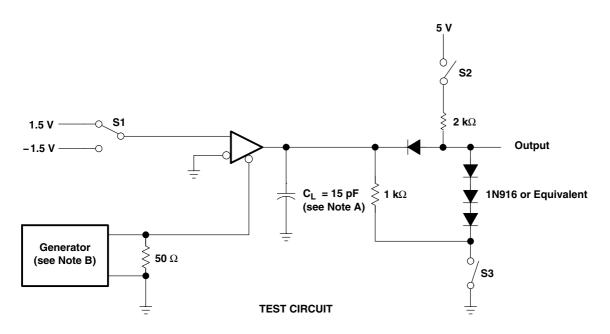


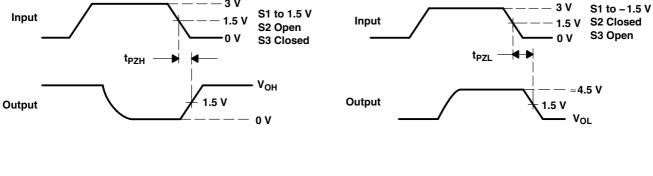
NOTES: A. C_L includes probe and jig capacitance.

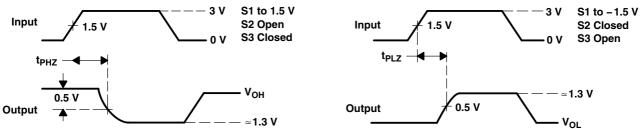
B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_r \leq$ 10 ns, $t_f \leq$ 10 ns, $Z_O =$ 50 Ω .

Figure 7. Receiver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION







VOLTAGE WAVEFORMS

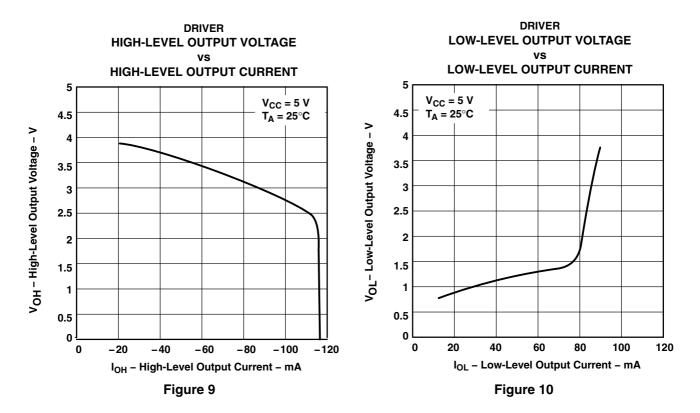
NOTES: A. C_L includes probe and jig capacitance.

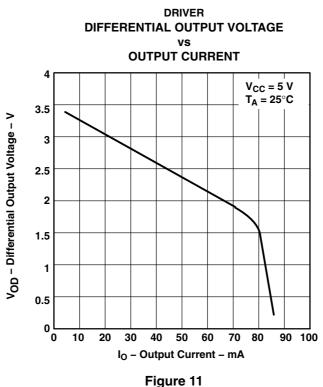
B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_r \leq$ 10 ns, $t_f \leq$ 10 ns, $Z_O =$ 50 Ω .

Figure 8. Receiver Test Circuit and Voltage Waveforms



TYPICAL CHARACTERISTICS†





[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.



TYPICAL CHARACTERISTICS[†]

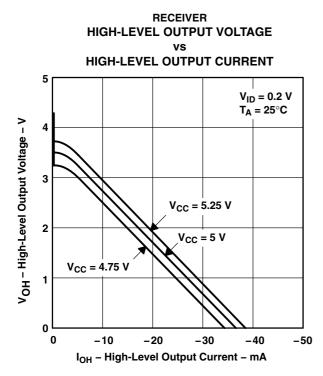
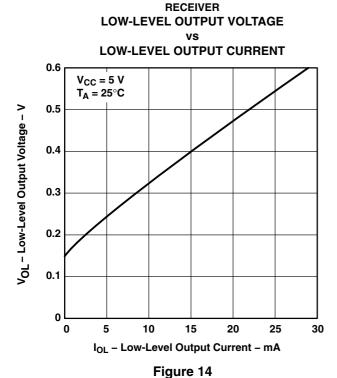


Figure 12



RECEIVER HIGH-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

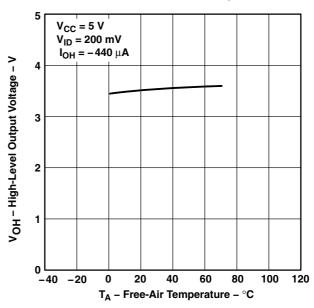


Figure 13

RECEIVER LOW-LEVEL OUTPUT VOLTAGE vs

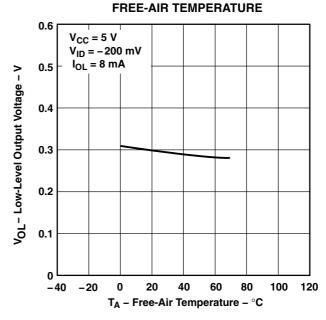
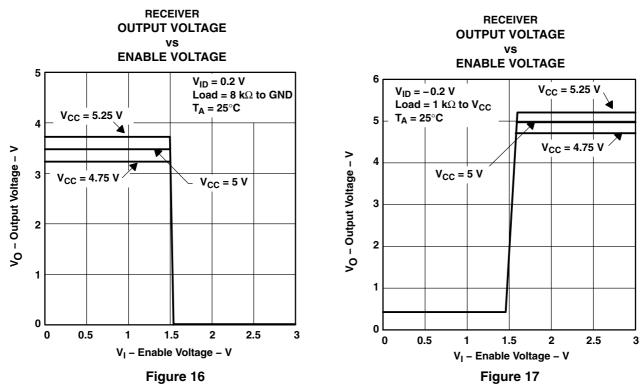


Figure 15

[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

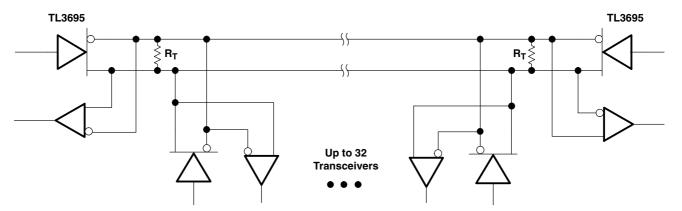


TYPICAL CHARACTERISTICS[†]



[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

APPLICATION INFORMATION



NOTE A: The line should be terminated at both ends in its characteristic impedance ($R_T = Z_O$). Stub lengths off the main line should be kept as short as possible.

Figure 18. Typical Application Circuit



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TL3695D	LIFEBUY	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3695	
TL3695DR	LIFEBUY	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3695	
TL3695DRG4	LIFEBUY	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3695	
TL3695P	LIFEBUY	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	TL3695P	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL3695DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jan-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL3695DR	SOIC	D	8	2500	340.5	336.1	25.0

PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jan-2022

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
TL3695D	D	SOIC	8	75	507	8	3940	4.32
TL3695P	Р	PDIP	8	50	506	13.97	11230	4.32



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



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